

PROCESS FOR REMOVING IMPURITIES FROM LOW DIELECTRIC CONSTANT FILMS DISPOSED ON SEMICONDUCTOR DEVICES

ABSTRACT OF THE DISCLOSURE

A process of removing impurities from a cured low dielectric constant organic polymeric film disposed on a semiconductor device. The process involves disposing a low dielectric constant curable organic polymeric film on an electrically conductive surface of a semiconductor device. The organic polymeric film is cured on the semiconductor device and thereupon contacted with supercritical carbon dioxide, optionally in the presence of at least one cosolvent.